

# MECHANICAL CASE OUTLINE

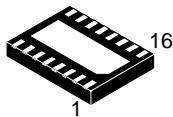
## PACKAGE DIMENSIONS

ON Semiconductor®

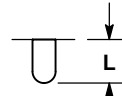
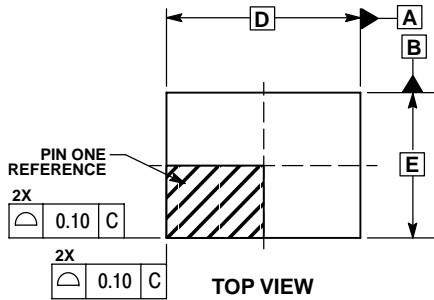


UDFN16 3.2x2.4, 0.4P  
CASE 517AL-01  
ISSUE O

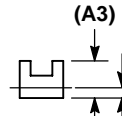
DATE 04 APR 2007



SCALE 4:1



DETAIL A  
OPTIONAL CONSTRUCTION  
2X SCALE

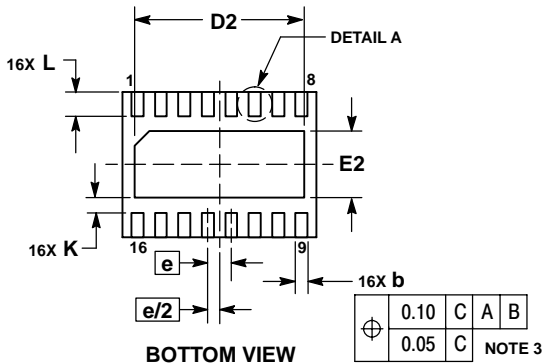
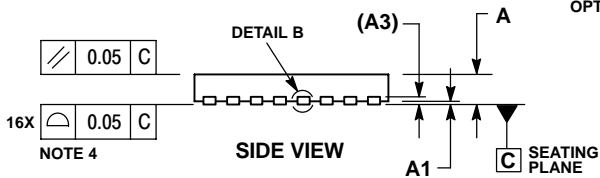


DETAIL B  
OPTIONAL CONSTRUCTION  
4X SCALE

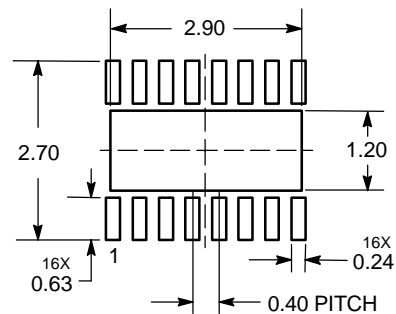
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13	REF
<i>b</i>	0.15	0.25
D	3.20	BSC
D2	2.70	2.90
E	2.40	BSC
E2	1.00	1.20
<i>e</i>	0.40	BSC
K	0.20	---
L	0.30	0.50



**SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON24329D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN16 3.2X2.4, 0.4P	PAGE 1 OF 2

